



Materials Declaration

Device:	ADL5500
Package:	WLCSP
Body Size (mm):	925umx925um
I/O Count:	4
Option:	Pb-Free

Chip				
Item	% of Chip	Weight (g)	PPM	
Silicon	100.0%	1.25 E-02	957008	

Wafer Bumps				
Item	% of Bumps	Weight (g)	PPM	
Sn	95.5%	0.000418193	31999	
Ag	4.0%	2.18949E-06	168	
Cu	0.5%	1.75159E-05	1340	
Sub-Total		4.38 E-04	33507	

UBM / Redistribution Layers				
Item	% of UBM / RDL	Weight (g)	PPM	
Al	10.1%	5.931 E-08	5	
Ni	22.3%	1.311 E-07	10	
V	0.7%	4.055 E-09	0	
Cu	66.9%	3.932 E-07	30	
Sub-Total		5.88 E-07	45	

Polyimide				
Item	% of Polyimide	Weight (g)	PPM	
n-Methylpyrrolidone	45.0%	5.55 E-05	4248	
Photosensitive Polyimide Resin	45.0%	5.55 E-05	4248	
Acrylate Ester	7.5%	9.25 E-06	708	
Proprietary Ingredient(s)	2.5%	3.084 E-06	236	
		1.23 E-04	9440	

Package Totals		
Total Weight (g)	PPM	
1.31 E-02	1000000	

ASE-CB-E

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

9/14/05

